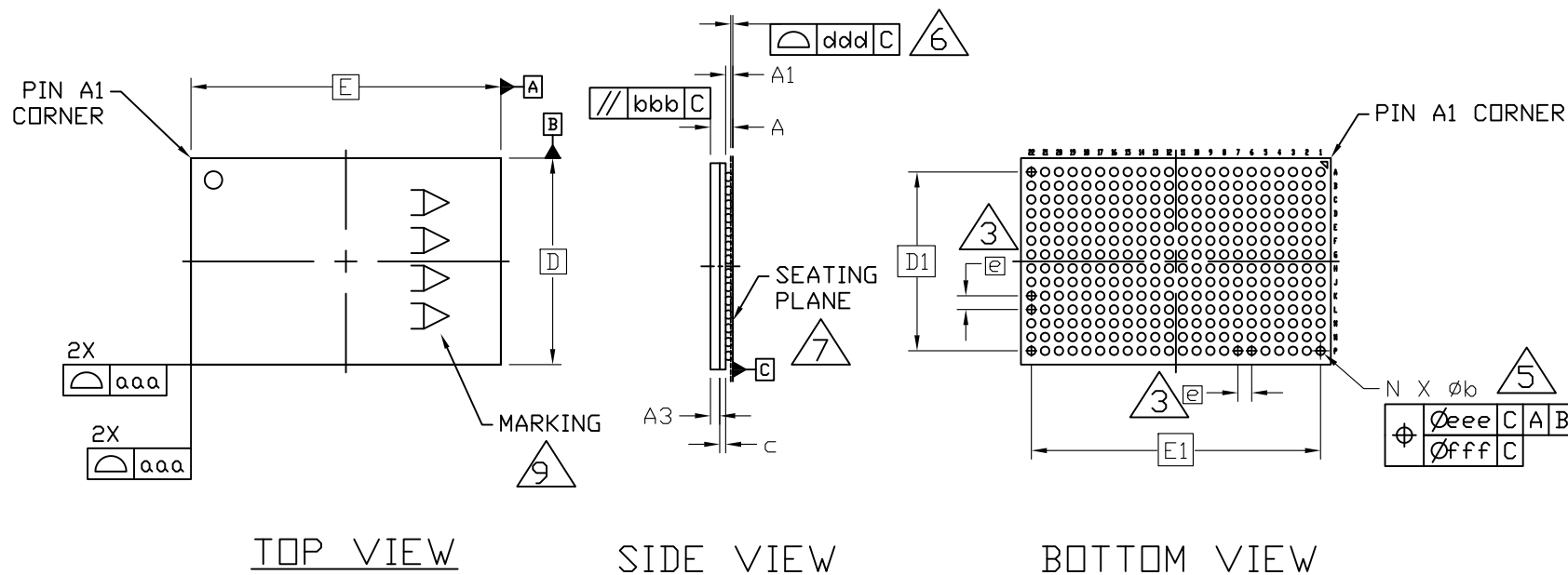




NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
- 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
- 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
- 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM [C] .
- DIMENSION 'ddd' IS MEASURED PARALLEL TO PRIMARY DATUM [C] .
- PRIMARY DATUM [C] (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSE BALLS.
- MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
- MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE EU ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
- ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE.
- PKG CODE: X30828FM+1

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.200	1.300	1.400
A1	0.360	--	0.460
A3	0.540 REF		
b	0.440	--	0.640
c	0.350 REF		
D	12.000 BSC		
D1	10.400 BSC		
E	18.000 BSC		
E1	16.800 BSC		
e	0.800 BSC		
aaa	0.150		
bbb	0.200		
ddd	0.150		
eee	0.150		
fff	0.080		
N	308		



TITLE:
PACKAGE OUTLINE, 308 BALLS FCCSP,
12x18x1.3mm

APPROVAL
EDEN CHEN
11/25/13

DOCUMENT CONTROL NO.
21-0749

REV. A 1/1

—DRAWING NOT TO SCALE—